









Release Date: 26 May 2015 Version: A1.0

PRODUCT DATASHEET



- ► PLCC4
- ➤ 3528+Lens 3.55t
- ► Infrared (850nm)

N0F17S66



3528+Lens 3.55t





3528 + Lens Series

APPLICATIONS:

- Security Device
- Sensor
- 3C Application

FEATURES:

Package: PLCC4 White SMT Package with Lens

Forward Current: 100mA Forward Voltage (typ.): 1.67V

Luminous Intensity (typ.): 30mW/sr@100mA

Colour: Infrared Wavelength: 850nm Viewing angle: 30°

Materials: Die: AlGaAs

Resin: Epoxy (Water Clear)

L/F Finish: Ag Plated

Operating Temperature: -40~+80°C **Storage Temperature:** -40~+85°C Soldering methods: Reflow soldering

Preconditioning: acc. to JEDEC Level 3

Packing: 12mm tape with 2000pcs/reel, ø330mm (13")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	100	mA
Peak Forward Current duty cycle 1% width 100μs	I _{FP}	1000	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	180	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	1.0	1.67	1.8	V	I _F =100mA
Radiated Intensity	I _V	25.5	30	35.9	mW/sr	IF=100mA
Peak Wavelength	λ_{P}	840	850	860	nm	IF=100mA
Spectral Bandwidth	Δλ		43		nm	IF=100mA
Viewing Angle	2θ _{1/2}		30		deg	IF=100mA

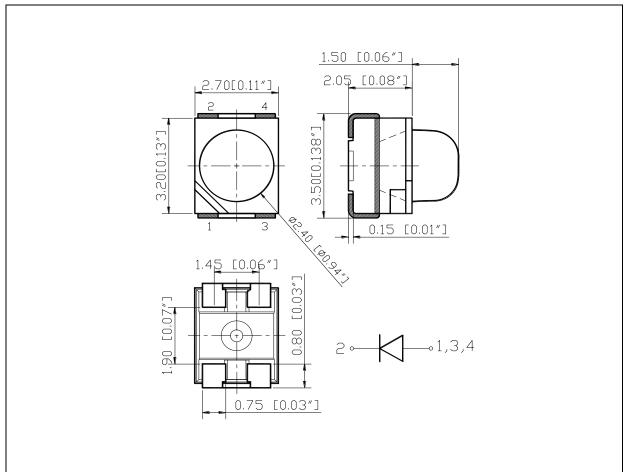
^{1.} Luminous intensity (I_V) $\pm 15\%$, Forward Voltage (V_F) ± 0.1 V, Viewing angle($2\theta_{1/2}$) $\pm 5\%$

^{2.} IS standard testing



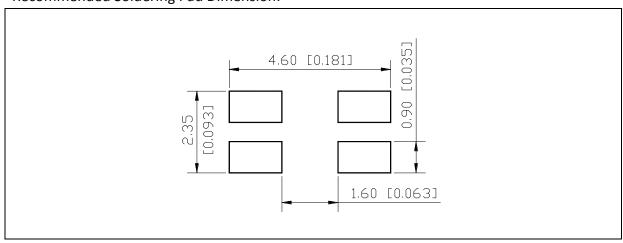
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

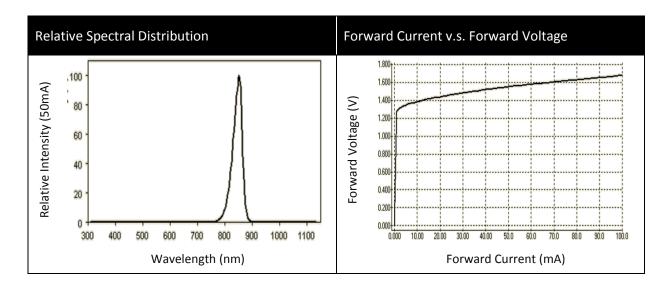
Recommended Soldering Pad Dimension:

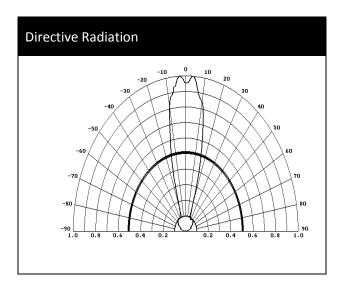


- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



ELECTRO-OPTICAL CHARACTERISTICS:

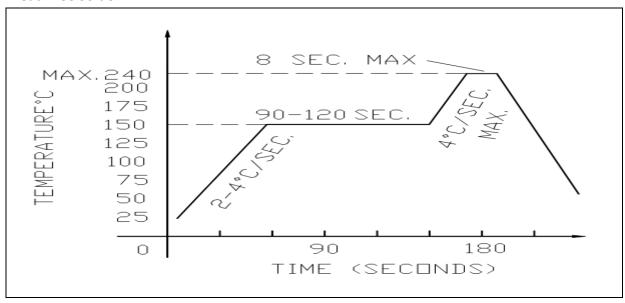






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



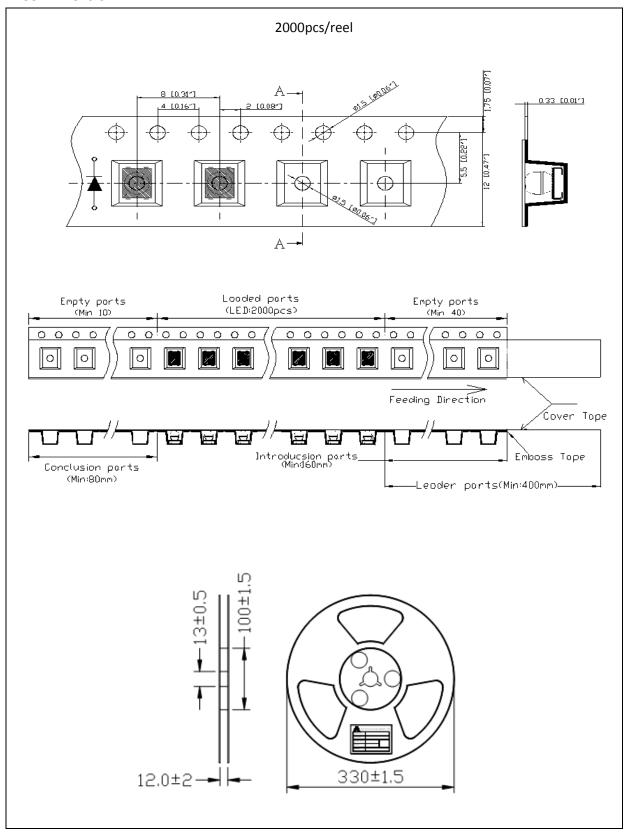
Note:

- 1. Maximum soldering temperature 240°C.
- 2. Maximum reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

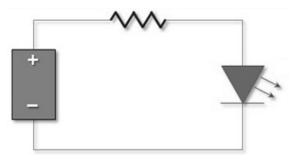
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	26/05/2015	Datasheet set-up.